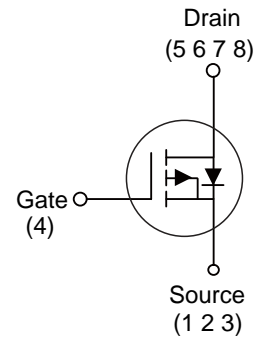


■ PRODUCT CHARACTERISTICS

V_{DSS}	-20V
$R_{DS(ON)}$ Typ(@ $V_{GS}=-2.5V$)	16.5m Ω
$R_{DS(ON)}$ Typ(@ $V_{GS}=-4.5V$)	14m Ω
I_D	-10A

Symbol

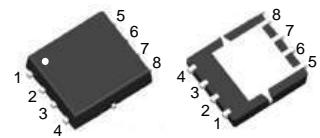


■ APPLICATIONS

- * PWM applications
- * Load switch
- * Power management

■ FEATURE

- * High power and current handling capability
- * Lead free product is acquired
- * Surface mount package



PDFN3X3

■ ORDER INFORMATION

Order Codes		Package	Packing
Halogen-Free	Halogen		
N/A	MOT2718J	PDFN3X3	5000 pieces/Reel

■ ABSOLUTE MAXIMUM RATINGS($T_A=25^{\circ}C$, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V_{DSS}	-20	V
Gate-Source Voltage	V_{GSS}	± 12	V
Drain Current Continuous(@ $V_{GS}=10V, T_A=25^{\circ}C$)	I_D	-10	A
Drain Current Continuous(@ $V_{GS}=10V, T_A=100^{\circ}C$)	I_D	-6.5	A
Drain Current Pulsed	I_{DM}	-40	A
Avalanche Energy *	E_{AS}	25	mJ
Power Dissipation	P_D	13	W
Junction Temperature	T_J	+150	$^{\circ}C$
Storage Temperature	T_{STG}	-55~ +150	$^{\circ}C$

■ THERMAL CHARACTERISTICS

Parameter	Symbol	Typ	Unit
Junction to Case	R_{thJC}	9.3	$^{\circ}C/W$

Note: * EAS condition: $T_J=25^{\circ}C, V_{DS}=15V, V_G=10V, L=0.5mH, R_g=25\Omega$

■ ELECTRICAL CHARACTERISTICS ($T_C=25^{\circ}\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Off characteristics						
Drain to Source Breakdown Voltage	V_{DSS}	$V_{GS}=0V, I_D=250\mu A$	-20	-	-	V
Drain to Source Leakage Current	I_{DSS}	$V_{DS}=-20V, V_{GS}=0V$	-	-	1	μA
Gate to Source Forward Leakage	$I_{GSS(F)}$	$V_{GS}=+12V, V_{DS}=0V$	-	-	100	nA
Gate to Source Reverse Leakage	$I_{GSS(R)}$	$V_{GS}=-12V, V_{DS}=0V$	-	-	-100	nA
On characteristics						
Drain to Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=-2.5V, I_D=-5A$	-	16.5	23	m Ω
		$V_{GS}=-4.5V, I_D=-5A$	-	14	18	m Ω
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.4	-0.64	-1.2	V
Dynamic characteristics						
Forward Transconductance	g_{fs}	$V_{DS}=-5V, I_D=-5A$	5	-	-	S
Input Capacitance	C_{iss}	$V_{DS}=-12V, V_{GS}=0V$ $f=1.0MHz$	-	1200	-	pF
Output Capacitance	C_{oss}		-	191	-	pF
Reverse Transfer Capacitance	C_{rss}		-	168	-	pF
Resistive Switching Characteristics						
Turn-on Delay Time	$t_{d(ON)}$	$V_{GS}=-4.5V, V_{DS}=-10V,$ $I_D=-5A, R_G=1\Omega$	-	12	-	ns
Rise Time	t_r		-	10	-	ns
Turn-off Delay Time	$t_{d(OFF)}$		-	25	-	ns
Fall Time	t_f		-	13	-	ns
Total Gate Charge	Q_g	$I_D=-5A, V_{DS}=-10V$ $V_{GS}=-4.5V$	-	10	-	nC
Gate to Source Charge	Q_{gs}		-	2	-	nC
Gate to Drain("Miller") Charge	Q_{gd}		-	2.7	-	nC
Source-Drain Diode Characteristics						
Continuous Source Current(Body Diode)	I_S		-	-	-10	A
Maximum Pulsed Current(Body Diode)	I_{SM}		-	-	-40	A
Diode Forward Voltage	V_{SD}	$I_{SD}=-1A, V_{GS}=0V$	-	-0.73	-1.2	V

■ TYPICAL CHARACTERISTICS

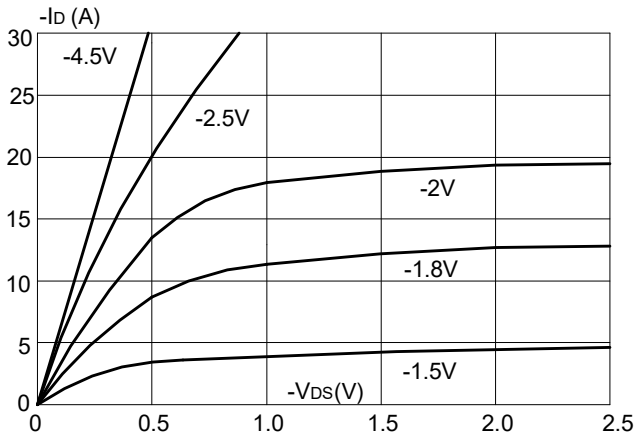


Figure 1: Output Characteristics

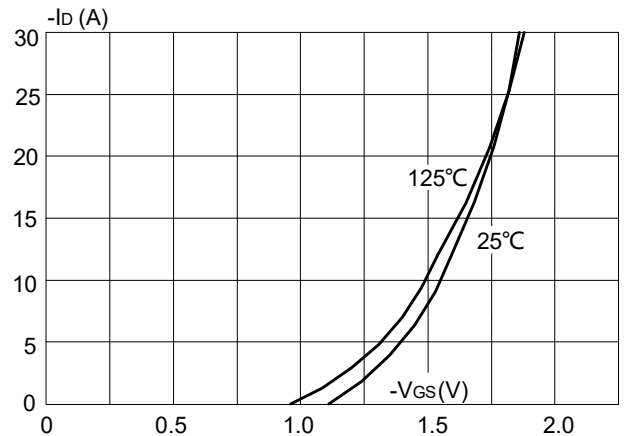


Figure 2: Typical Transfer Characteristics

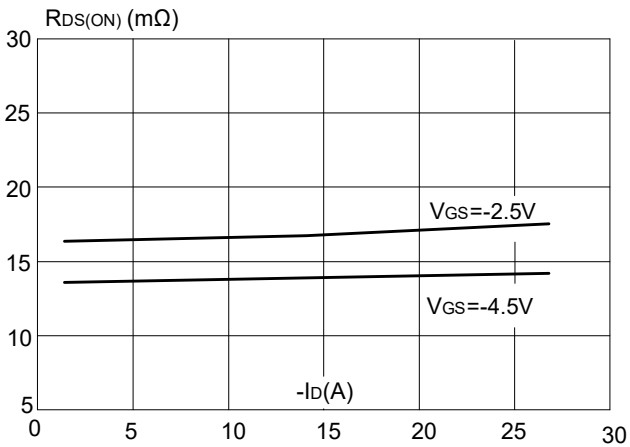


Figure 3: On-resistance vs. Drain Current

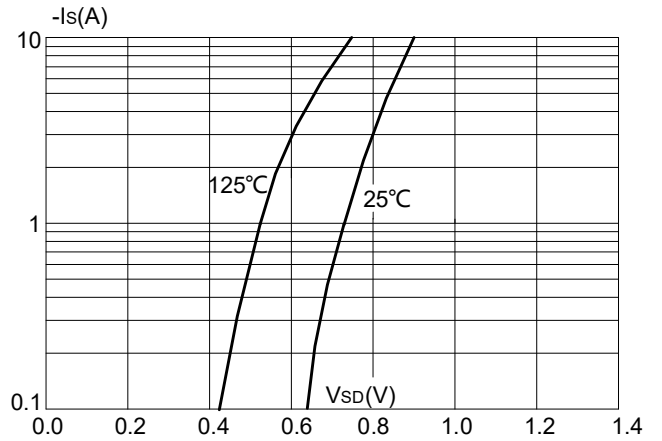


Figure 4: Body Diode Characteristics

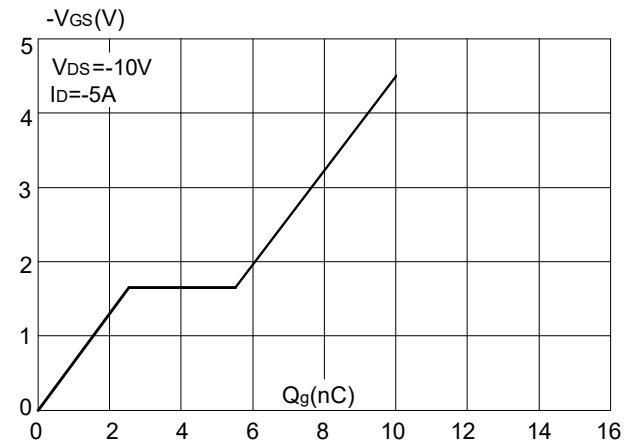


Figure 5: Gate Charge Characteristics

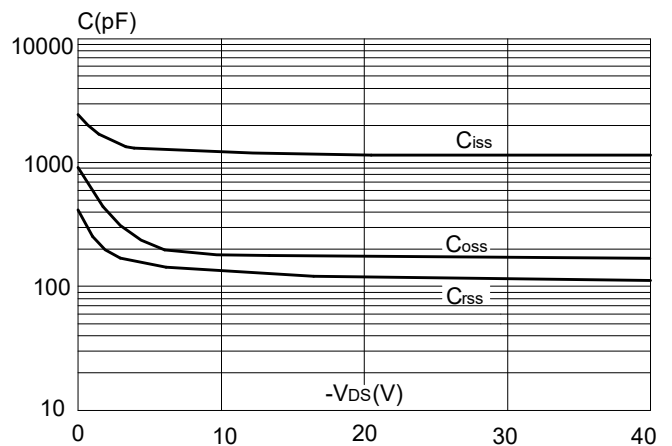


Figure 6: Capacitance Characteristics

■ TYPICAL CHARACTERISTICS(Cont.)

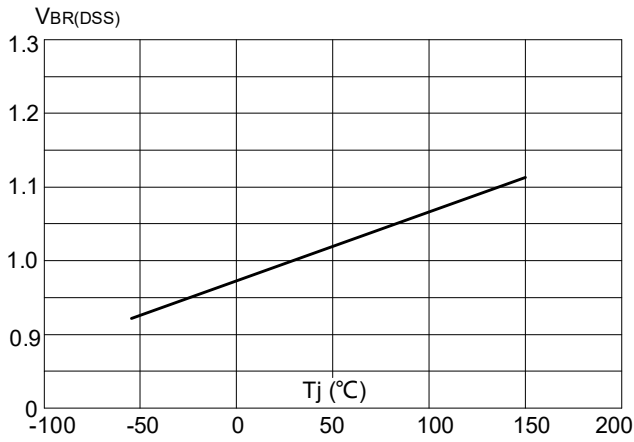


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

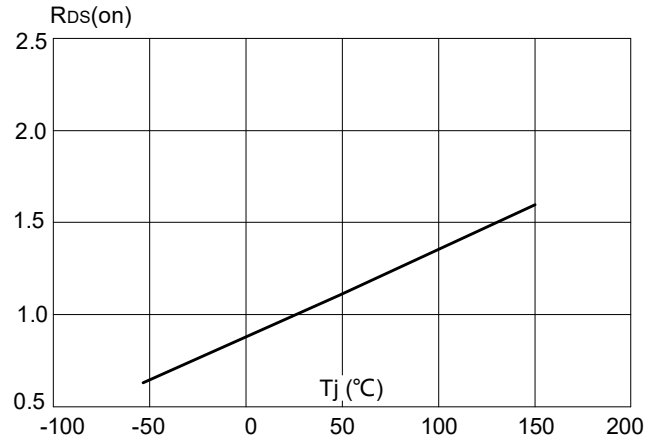


Figure 8: Normalized on Resistance vs. Junction Temperature

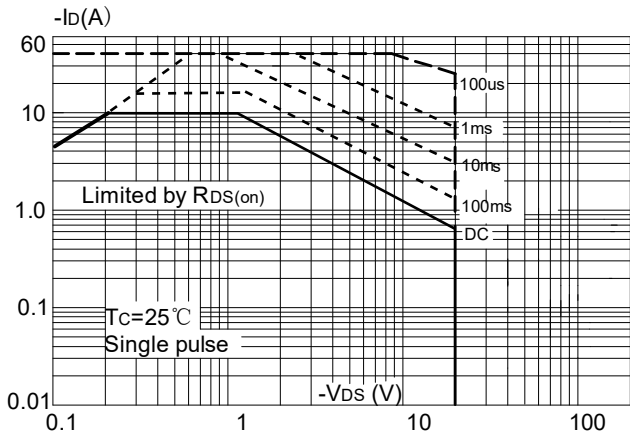


Figure 9: Maximum Safe Operating Area

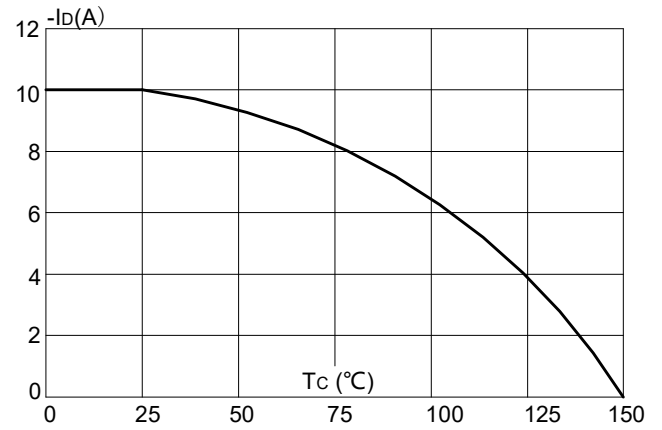
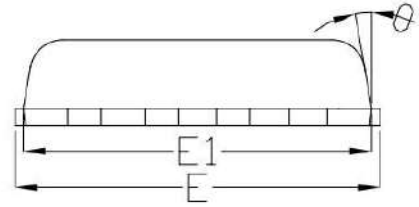
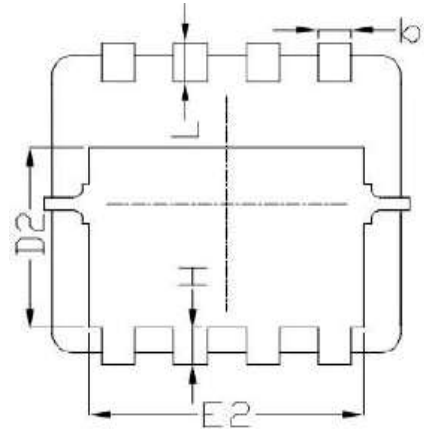
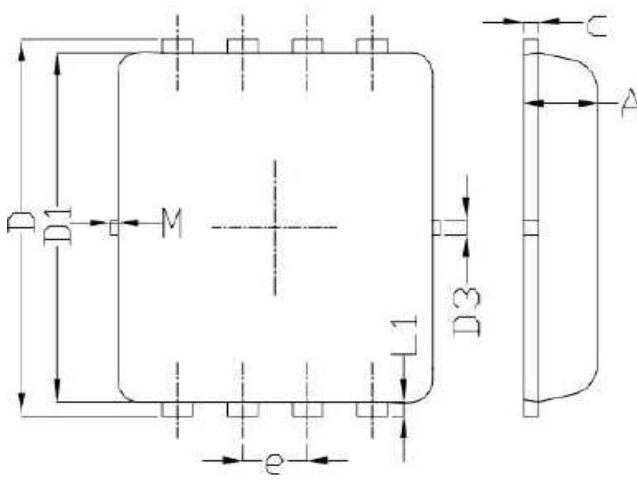
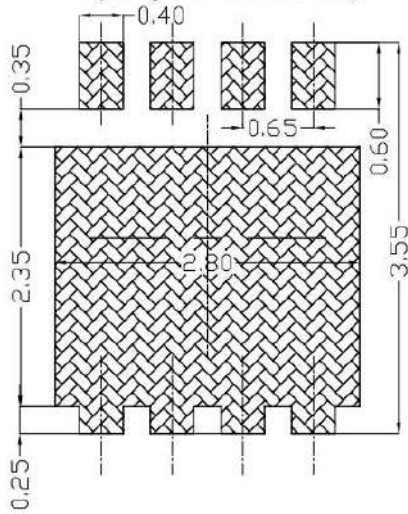


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

■ PDFN3X3 PACKAGE OUTLINE DIMENSIONS



Land Pattern
(Only for Reference)



SYMBOL	DIMENSIONAL REQMTS		
	MIN	NOM	MAX
A	0.70	0.75	0.80
b	0.25	0.30	0.35
c	0.10	0.15	0.25
D	3.25	3.35	3.45
D1	3.00	3.10	3.20
D2	1.78	1.88	1.98
D3	---	0.13	---
E	3.20	3.30	3.40
E1	3.00	3.15	3.20
E2	2.39	2.49	2.59
e	0.65BSC		
H	0.30	0.39	0.50
L	0.30	0.40	0.50
L1	---	0.13	---
θ	---	10°	12°
M	*	*	0.15
* Not specified			